IN THE SPECIFICATION

Please replace the paragraph at page 1, lines 12-28, with the following amended paragraph:

-- This application is a Continuation of copending U.S. Patent Application Serial No. 10/229,453 filed on August 28, 2002, which is a Continuation-In-Part of U.S. Patent Application Serial No. 10/001,180~~, entitled "Electrical Connection For Inkjet Printhead Assembly With Hybrid Carrier For Printhead Dies"~~ filed on November 1, 2001, now U.S. Patent No. 6,523,940, which is a Continuation of U.S. Patent Application Serial No. 09/648,120~~, entitled "Electrical Connection For Wide-Array Inkjet Printhead Assembly With Hybrid Carrier For Printhead Dies"~~ filed on August 25, 2000, now U.S. Patent No. 6,341,845, ~~both assigned to the assignee of the present invention, and incorporated herein by reference,~~ and ~~is~~ a Continuation-In-Part of U.S. Patent Application Serial No. 09/648,564~~, entitled "Inkjet Printhead Assembly With Hybrid Carrier for Printhead Dies"~~ filed on August 25, 2000, now U.S. Patent No. 6,464,333, which is a Continuation-in-Part of U.S. Patent Application Serial No. 09/216,606~~, entitled "Multilayered Platform for Multiple Printhead Dies"~~ filed on December 17, 1998, now U.S. Patent No. 6,322,206, and a Continuation-in-Part of U.S. Patent Application Serial No. 09/216,601~~, entitled "Inkjet Printing Apparatus with Ink Manifold"~~ filed on December 17, 1998, now U.S. Patent No. 6,250,738, each assigned to the assignee of the present invention, and incorporated herein by reference. --